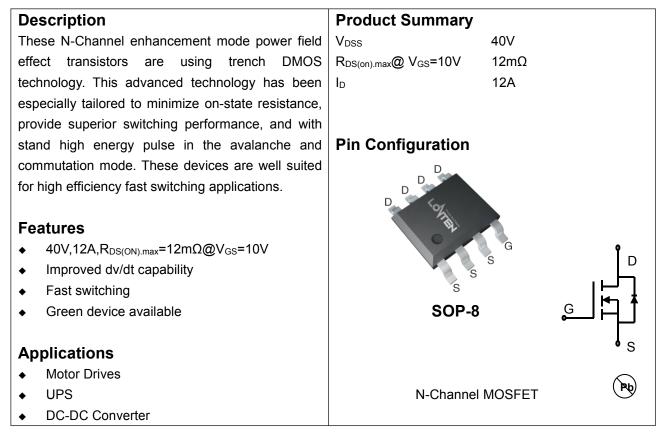


# LNL04R120

# Lonten N-channel 40V, 12A, 12m<sub>Ω</sub> Power MOSFET



### Absolute Maximum Ratings T<sub>A</sub>= 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	VDSS	40	V
Continuous drain current ( T <sub>A</sub> =25°C )	۱ <sub>۵</sub>	12	A
Continuous drain current ( $T_A = 100^{\circ}C$ )		7.6	А
Pulsed drain current <sup>1)</sup>	I <sub>DM</sub>	48	А
Gate-Source voltage	V <sub>GSS</sub>	±20	V
Power Dissipation ( T <sub>A</sub> =25°C )	PD	2.1	W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{ ext{ heta}JA}$	59.5	°C/W



## Package Marking and Ordering Information

Device	Device Package	Marking
LNL04R120	SOP-8	LNL04R120

## Electrical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics				1		
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	40			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.0		2.0	V
Drain-source leakage current		V <sub>DS</sub> =40 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 25°C			1	μA
	IDSS	V <sub>DS</sub> =32 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 125°C			10	μA
Gate leakage current, Forward	IGSSF	V <sub>GS</sub> =20 V, V <sub>DS</sub> =0 V			100	nA
Gate leakage current, Reverse	Igssr	V <sub>GS</sub> =-20 V, V <sub>DS</sub> =0 V			-100	nA
	P	V <sub>GS</sub> =10 V, I <sub>D</sub> =12 A		9.2	12	mΩ
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5 V, I <sub>D</sub> =8 A		11.8	16	mΩ
Forward transconductance	<b>g</b> fs	V <sub>DS</sub> =5 V , I <sub>D</sub> =20A		35		S
Dynamic characteristics		· · · · · ·				
Input capacitance	C <sub>iss</sub>			1370		
Output capacitance	Coss	$V_{DS} = 20 V, V_{GS} = 0 V,$		158		pF
Reverse transfer capacitance	Crss	F = 1MHz		125		
Turn-on delay time	t <sub>d(on)</sub>			14.5		- ns
Rise time	tr	)/ = 20)/)/=10)/  - =12 A		19.2		
Turn-off delay time	t <sub>d(off)</sub>	$V_{DD} = 20V, V_{GS} = 10V, I_D = 12 A$		61		
Fall time	t <sub>f</sub>			27		
Gate resistance	Rg	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz		3.5		Ω
Gate charge characteristics						
Gate to source charge	Q <sub>gs</sub>			7.1		
Gate to drain charge	Q <sub>gd</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =12A,		2.9		nC
Gate charge total	Qg	- V <sub>GS</sub> = 10V		27.5		
Drain-Source diode characterist	tics and Maxin	num Ratings				•
Continuous Source Current	ls				12	А
Pulsed Source Current <sup>3)</sup>	I <sub>SM</sub>				48	А
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A, T <sub>J</sub> =25℃			1.2	V
Reverse Recovery Time	trr			21		ns
Reverse Recovery Charge	Qrr	I₅=12A,di/dt=100A/us, Tյ=25℃		7.8		nC

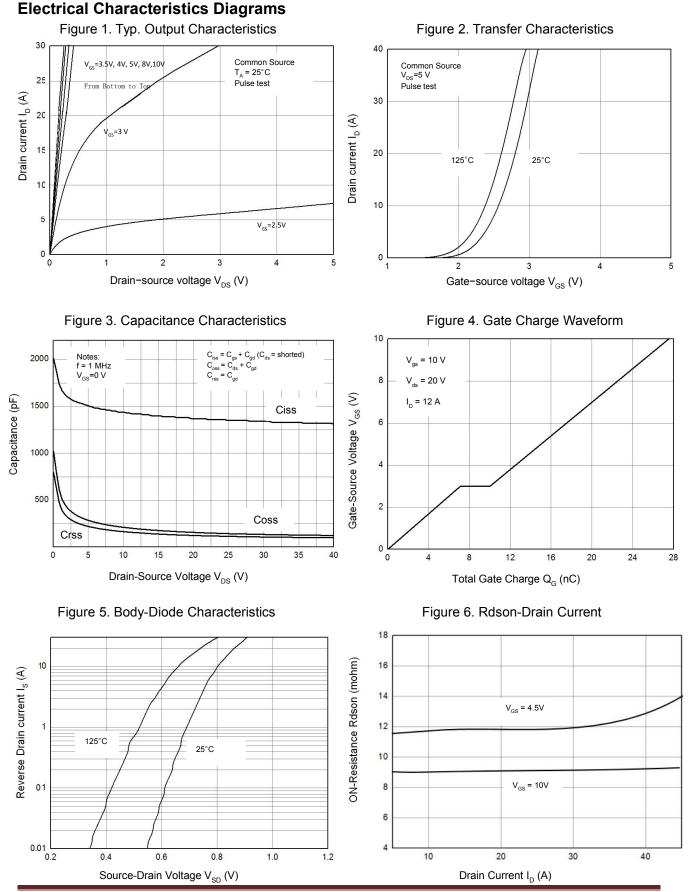
Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: Pulse Test: Pulse Width  $\leq$ 300  $\mu$  s, Duty Cycle $\leq$ 2%.



# LNL04R120

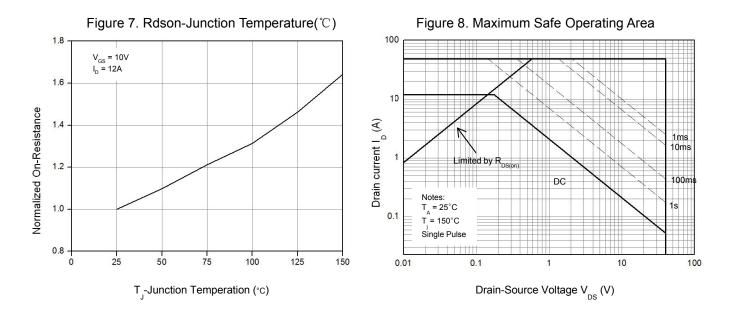


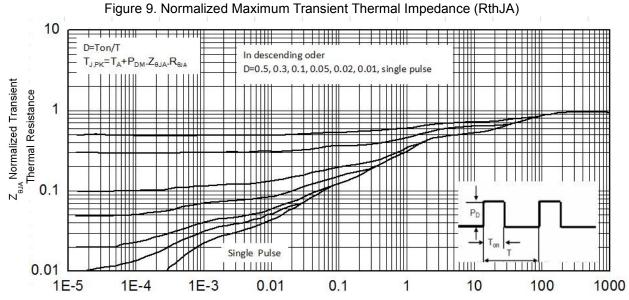
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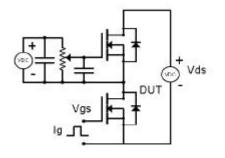


Pulse Width t (s)



### **Test Circuit & Waveform**

Figure 8. Gate Charge Test Circuit & Waveform



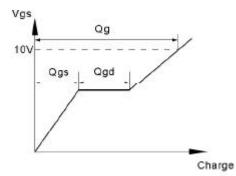
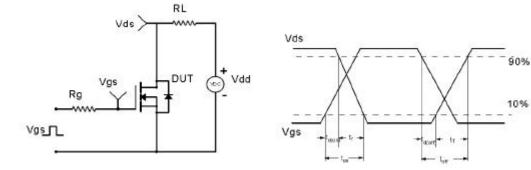
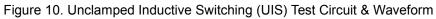
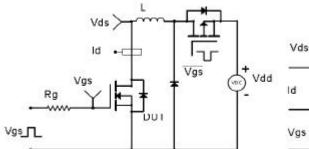


Figure 9. Resistive Switching Test Circuit & Waveforms







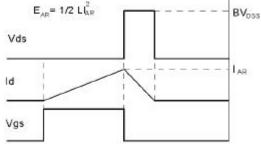
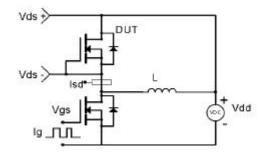
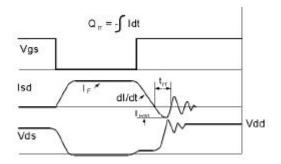


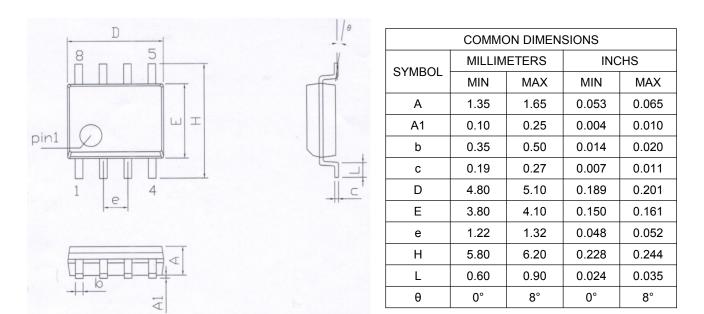
Figure 11. Diode Recovery Circuit & Waveform



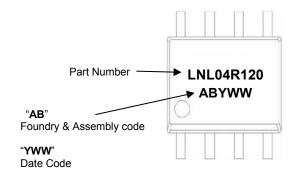




# **Mechanical Dimensions for SOP-8**



#### **SOP-8 Part Marking Information**





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